

DECLARATION FOR PATENT APPLICATION

Docket Number (Optional)
MR2685-105

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD FOR PREPARING THIN FIBER-STRUCTURED POLYMER WEB, the specification of which is attached hereto unless the following box is checked:

☐ was filed on _____ as United States Application Number or PCT International Application Number _____ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56.

I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)			Priority Not Claimed
<u>2001-3685</u>	<u>KR</u>	<u>26 January 2001</u>	<input type="checkbox"/>
(Number)	(Country)	(Day/Month/Year Filed)	
			<input type="checkbox"/>
(Number)	(Country)	(Day/Month/Year Filed)	

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below.

(Application Number) _____ (Filing Date) _____

(Application Number) _____ (Filing Date) _____

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. § 112.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

(Application Number) _____ (Filing Date) _____ (Status: *patented, pending, abandoned*) _____

(Application Number) _____ (Filing Date) _____ (Status: *patented, pending, abandoned*) _____

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

MORTON J. ROSENBERG, ESQ., REG. # 26,049;
DAVID I. KLEIN, ESQ., REG. # 33,253; JUN Y. LEE, ESQ., REG. # 40,262
MORTON J. ROSENBERG at telephone number 410-465-6678
ROSENBERG, KLEIN & LEE
3458 ELLICOTT CENTER DRIVE-SUITE 101
ELLICOTT CITY, MD 21043
FAX #: 410-461-3067
E-MAIL ADDRESS: rkl@rklpatlaw.com

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor (given name, family name) Wha Seop LEE (LEE IS FAMILY NAME)
Inventor's signature Lee Whaseop Date December 10, 2001
Residence Seoul, Korea Citizenship Korea
Post Office Address Samsungcheongdamgongwon Apt. 103-601, 60 Cheongdam-dong, Kangnam-ku, Seoul, Korea

Full name of second joint inventor, if any (given name, family name) Seong Mu JO (JO IS FAMILY NAME)
Second inventor's signature Seong Mu JO Date December 10, 2001
Residence Seoul, Korea Citizenship Korea
Post Office Address 168-174 Seongbuk 1-dong, Seongbuk-ku, Seoul, Korea

☒ Additional Inventors are being named on separately numbered sheets attached hereto.

Third Joint Inventor Suk Won CHUN (CHUN IS FAMILY NAME)

Inventor's Signature

Suk Won Chun

Date

December 10, 2001

Residence Seoul, Korea

Citizenship Korea

Post Office Address Byouksan APT. 13-1504, Suyou 2-dong, Kangbuk-ku, Seoul, Korea

Fourth Joint Inventor Sung Won CHOI (CHOI IS FAMILY NAME)

Inventor's Signature

Choi Sung Won

Date

December 10, 2001

Residence Kyungki-do, Korea

Citizenship Korea

Post Office Address Taeyoung APT. 1707-1702, Ilsan 3-dong, Ilsan-ku, Koyang-si, Kyungki-do, Korea

Fifth Joint Inventor

Inventor's Signature

Date

Residence

Citizenship

Post Office Address

Sixth Joint Inventor

Inventor's Signature

Date

Residence

Citizenship

Post Office Address